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March 2016 **QFET**™

FQB34P10TM F085

100V P-Channel MOSFET

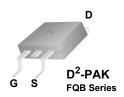
General Description

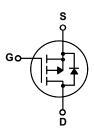
These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor control.

Features

- -33.5A, -100V, $R_{DS(on)} = 0.06\Omega @V_{GS} = -10 V$
- Low gate charge (typical 85 nC)
- Low Crss (typical 170 pF)
- Fast switching
- · 100% avalanche tested
- Improved dv/dt capability
- · 175°C maximum junction temperature rating
- Qualified to AEC Q101
- · RoHS Compliant





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter Drain-Source Voltage		FQB34P10TM_F085	Units V	
V_{DSS}			-100		
I _D	Drain Current - Continuous (T _C = 25°C)		-33.5	Α	
	- Continuous (T _C = 100°C)		-23.5	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	-134	Α	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	2200	mJ	
I _{AR}	Avalanche Current	(Note 1)	-33.5	Α	
E _{AR}	Repetitive Avalanche Energy	valanche Energy (Note 1)		mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-6.0	V/ns	
P _D	Power Dissipation (T _A = 25°C) *		3.75	W	
	Power Dissipation (T _C = 25°C)		155	W	
	- Derate above 25°C		1.03	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.97	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = -250 μA	-100			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C		-0.1		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -100 V, V _{GS} = 0 V			-1	μА
_ 55		V _{DS} = -80 V, T _C = 150°C			-10	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-2.0		-4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -16.75 A		0.049	0.06	Ω
9 _{FS}	Forward Transconductance	V _{DS} = -40 V, I _D = -16.75 A (Note 4)		23		S
Dynam C _{iss}	ic Characteristics Input Capacitance	V - 25 V V - 0 V		2240	2910	pF
C _{oss}	Output Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		730	950	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1.5 WH 12		170	220	pF
	ng Characteristics		l			
t _{d(on)}	Turn-On Delay Time	V 50.V I 00.5 A		25	60	ns
t _r	Turn-On Rise Time	$V_{DD} = -50 \text{ V}, I_{D} = -33.5 \text{ A},$ $R_{G} = 25 \Omega$		250	510	ns
t _{d(off)}	Turn-Off Delay Time	RG - 25 12		160	330	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		210	430	ns
Q _g	Total Gate Charge	V _{DS} = -80 V, I _D = -33.5 A,		85	110	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		15		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		45		nC
Drain-S	ource Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				-33.5	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				-134	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -33.5 A			-4.0	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = -33.5 \text{ A},$		160		ns
_		†aa	l	-		+

Q_{rr}

- $\label{eq:Notes:$

Reverse Recovery Charge

 $dI_F / dt = 100 A/\mu s$

(Note 4)

0.88

μС

Typical Characteristics

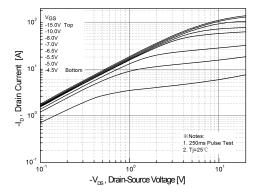


Figure 1. On-Region Characteristics

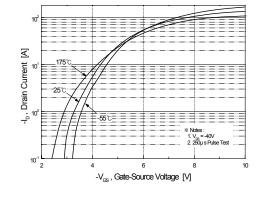


Figure 2. Transfer Characteristics

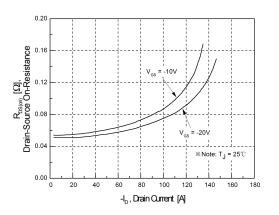


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

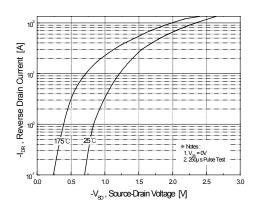


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

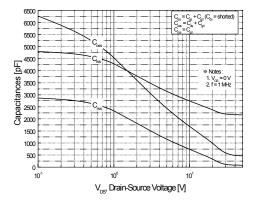


Figure 5. Capacitance Characteristics

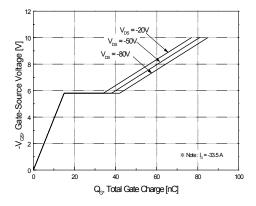


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

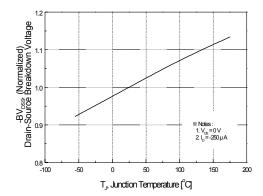


Figure 7. Breakdown Voltage Variation vs. Temperature

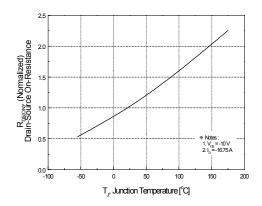


Figure 8. On-Resistance Variation vs. Temperature

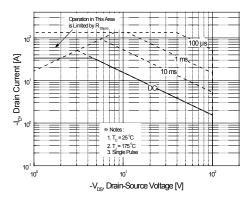


Figure 9. Maximum Safe Operating Area

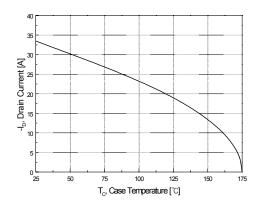


Figure 10. Maximum Drain Current vs. Case Temperature

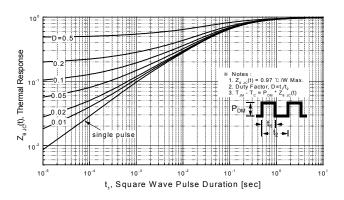
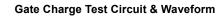
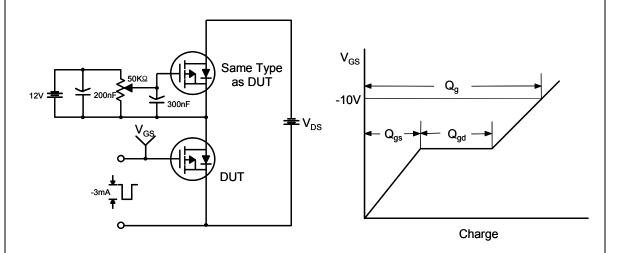
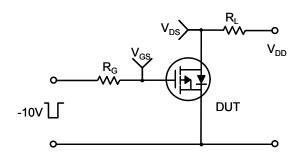


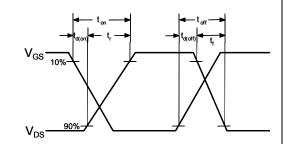
Figure 11. Transient Thermal Response Curve



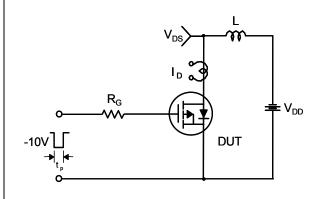


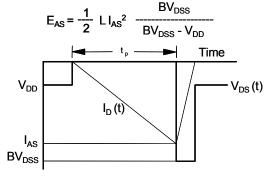
Resistive Switching Test Circuit & Waveforms



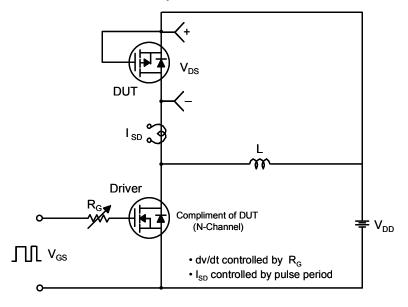


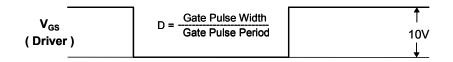
Unclamped Inductive Switching Test Circuit & Waveforms

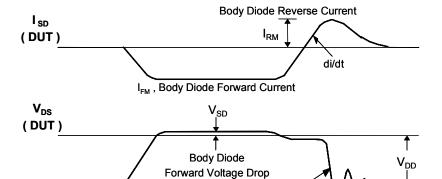




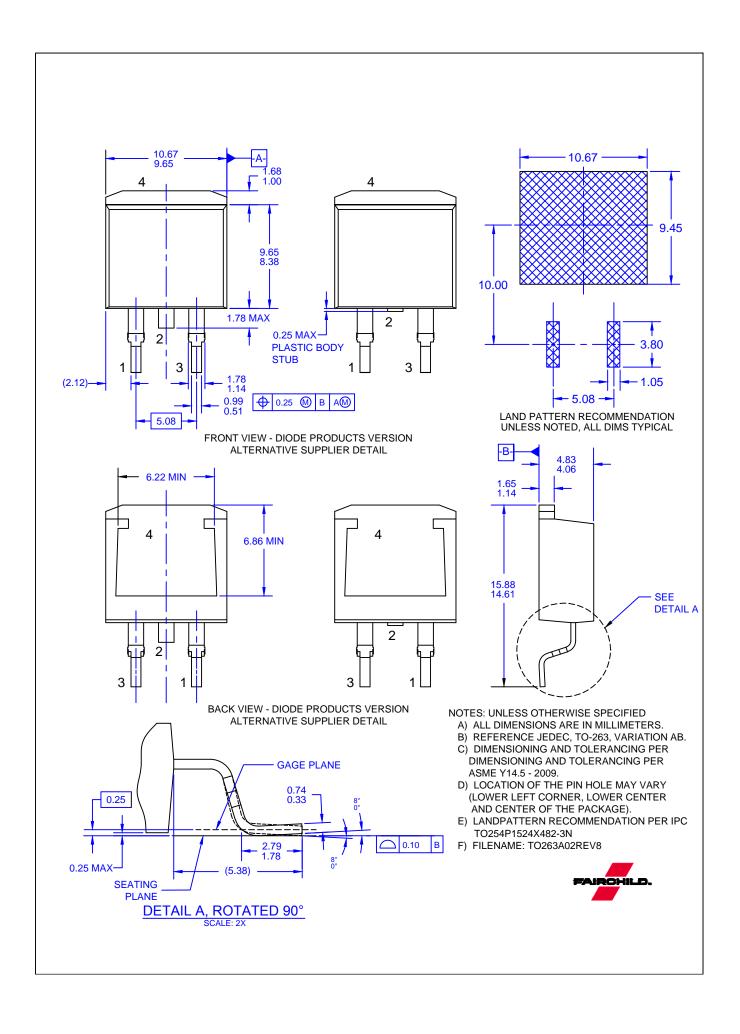
Peak Diode Recovery dv/dt Test Circuit & Waveforms







Body Diode Recovery dv/dt



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